Zytel® HTNFE8200 BK431

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTNFE8200 BK431 is an unreinforced, toughened, heat stabilized high performance polyamide resin for injection molding. It is also a PPA resin.

Product information

Resin Identification	PA6T/XT-I	ISO 1043
Part Marking Code	>PA6T/XT-I<	ISO 11469
Part Marking Code	>PPA-I<	SAE J1344
ISO designation	ISO 16396-PA6T/XT-I,,M1CG1HR,S10-020	

Rheological properties

	dry/cond.		
Molding shrinkage, parallel	1.0 / -	%	ISO 294-4, 2577
Molding shrinkage, normal	1.0 / -	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile modulus	319000 / -	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	10000 / -	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	5.5 / -	%	ISO 527-1/-2
Nominal strain at break	14 / -	%	ISO 527-1/-2
Flexural modulus	305000 / -	psi	ISO 178
Charpy impact strength, 23 °C	N / N	ftlb/in²	ISO 179/1eU
Charpy impact strength, -30 °C	N / N	ftlb/in²	ISO 179/1eU
Charpy notched impact strength, 23 °C	38.1 / -	ftlb/in²	ISO 179/1eA

Thermal properties

	dry/cond.		
Melting temperature, 10 °C/min	572 / *	°F	ISO 11357-1/-3
Melting temperature, first heat	572 / *	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	257 / *	°F	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	280 / *	°F	ISO 75-1/-2
Thermal conductivity, flow	0.27	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2900	J/(kg K)	ISO 22007-4
Specific heat capacity solid	1520	J/(kg K)	ISO 22007-4

Flammability

	dry/cond.		
Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.0295 / *	in	IEC 60695-11-10
FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	<80[DS]	in/min	ISO 3795 (FMVSS 302)

[DS]: Derived from similar grade

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Electrical properties

	dry/cond.		
Volume resistivity	>1E13 / -	Ohm.m	IEC 62631-3-1

Physical/Other properties

	dry/cond.		
Density	0.0408 / -	lb/in³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Melt Temperature Optimum	617	°F
Min. melt temperature	608	°F
Max. melt temperature	626	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold Pressure Time (h is the max. wall thickness of the part in mm)	h^2+2	s

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Ford	WSS-M98P14-A3	
General Motors	GMW16799P-PPA-T2	Black

Characteristics

Processing	Injection Molding
Special characteristics	High impact or impact modified, Heat stabilized or stable to heat

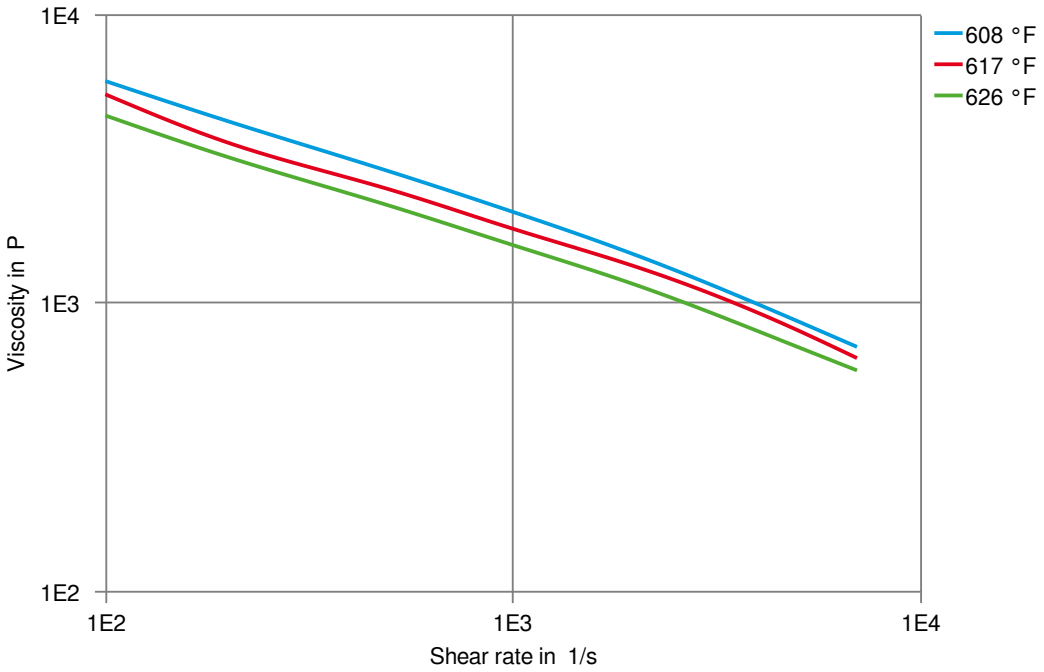
Additional information

Injection molding	During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

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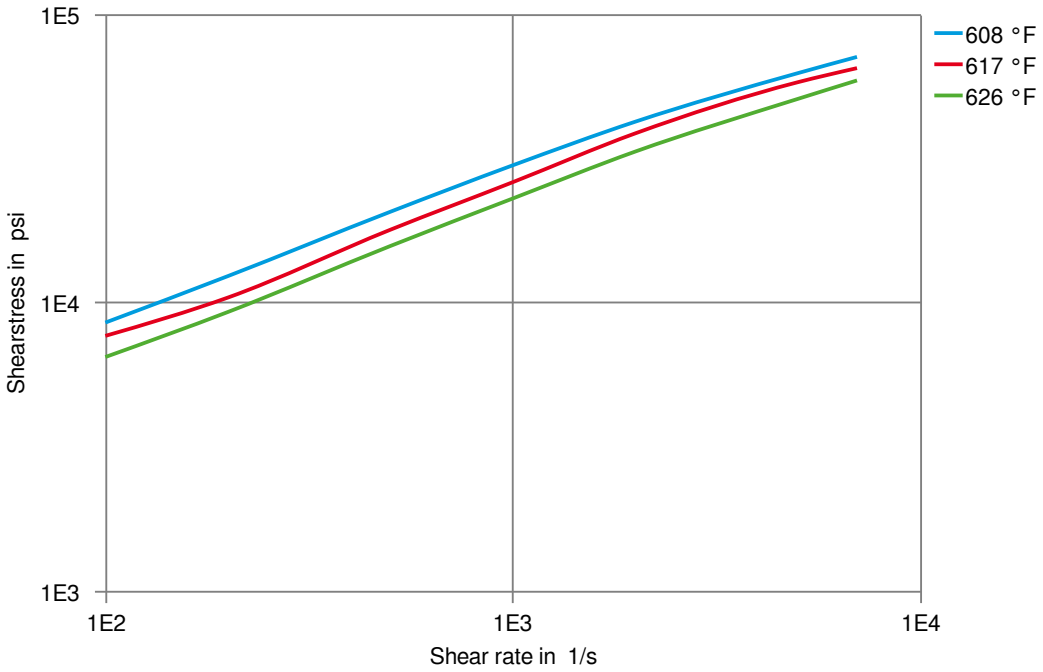
Viscosity-shear rate



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Shearstress-shear rate



Revised: 2025-08-26 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colorants or other additives may cause significant variations in data values. Properties of molded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
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